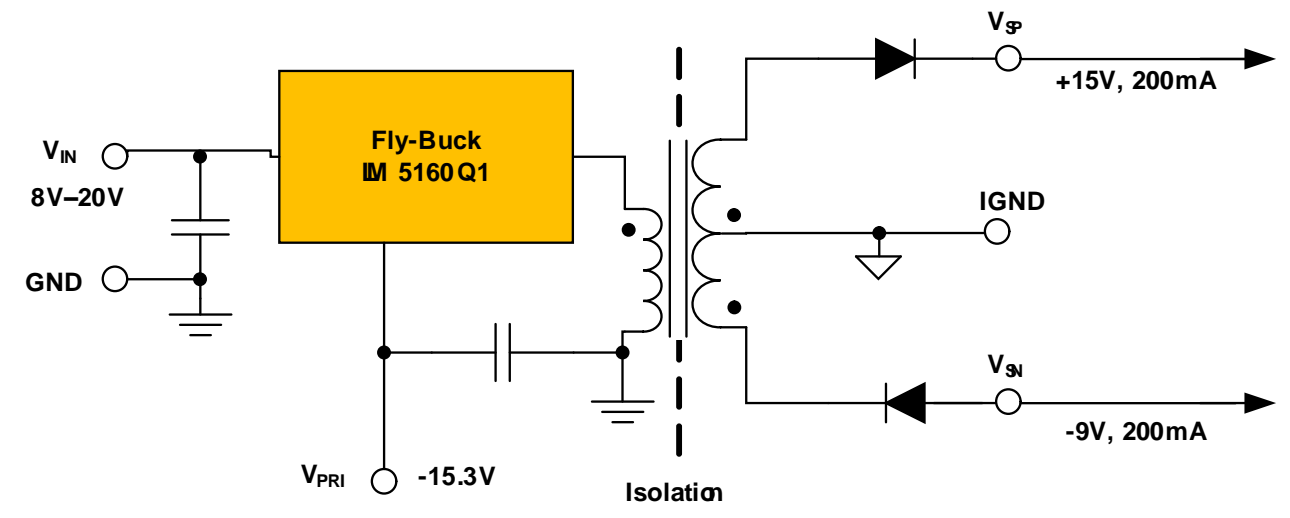
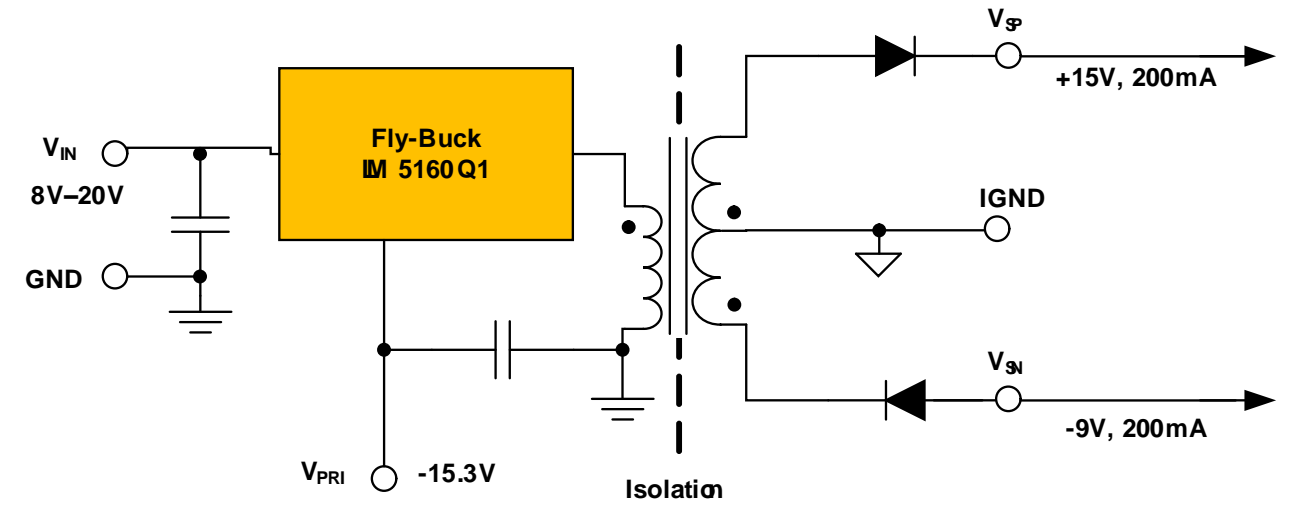


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

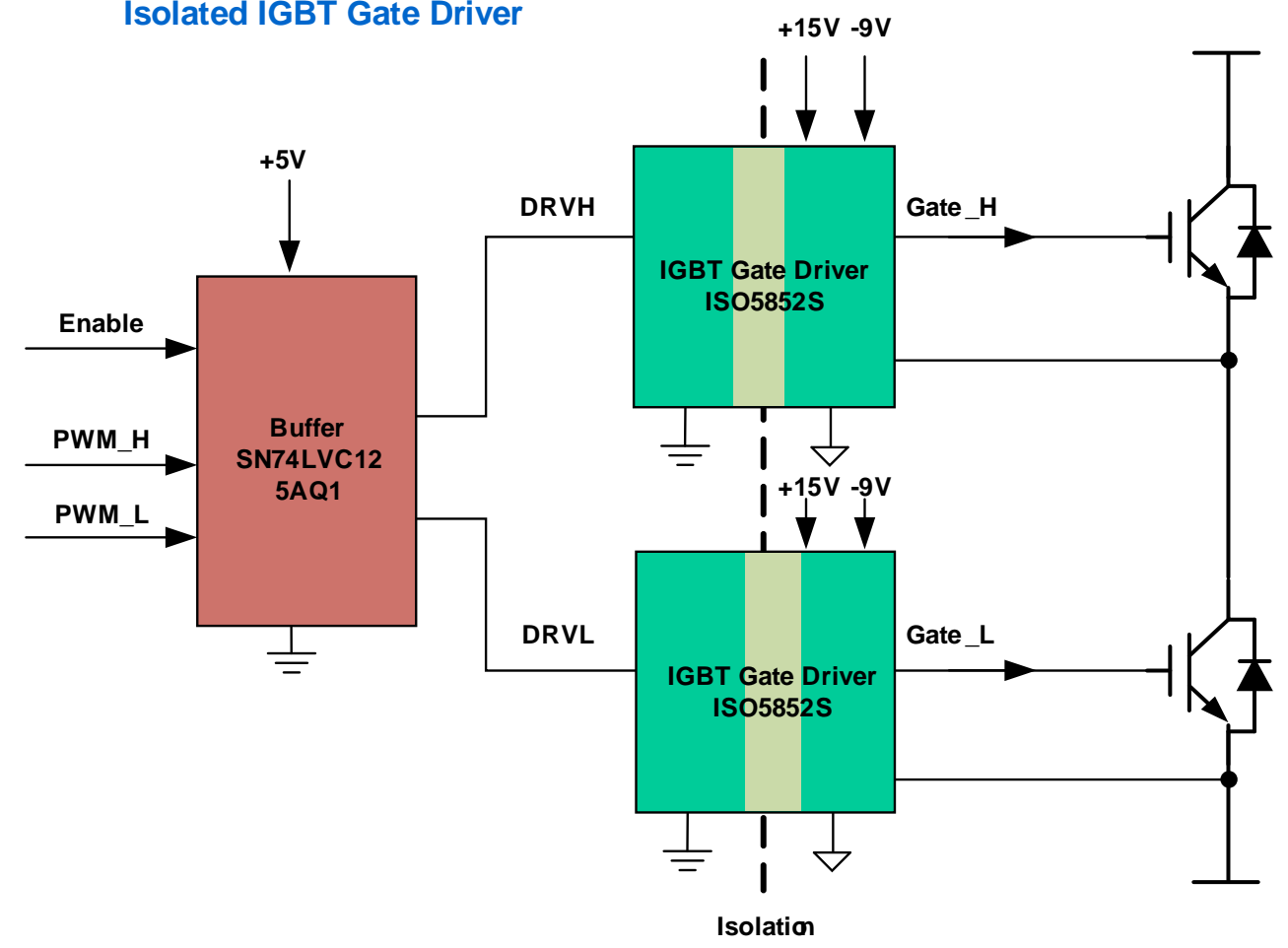
**Isolated Fly-buck Converter**



**Isolated Fly-buck Converter**

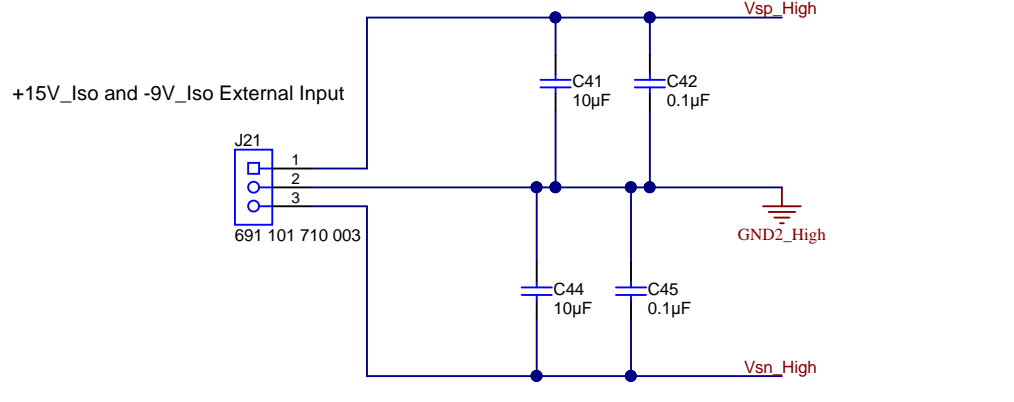
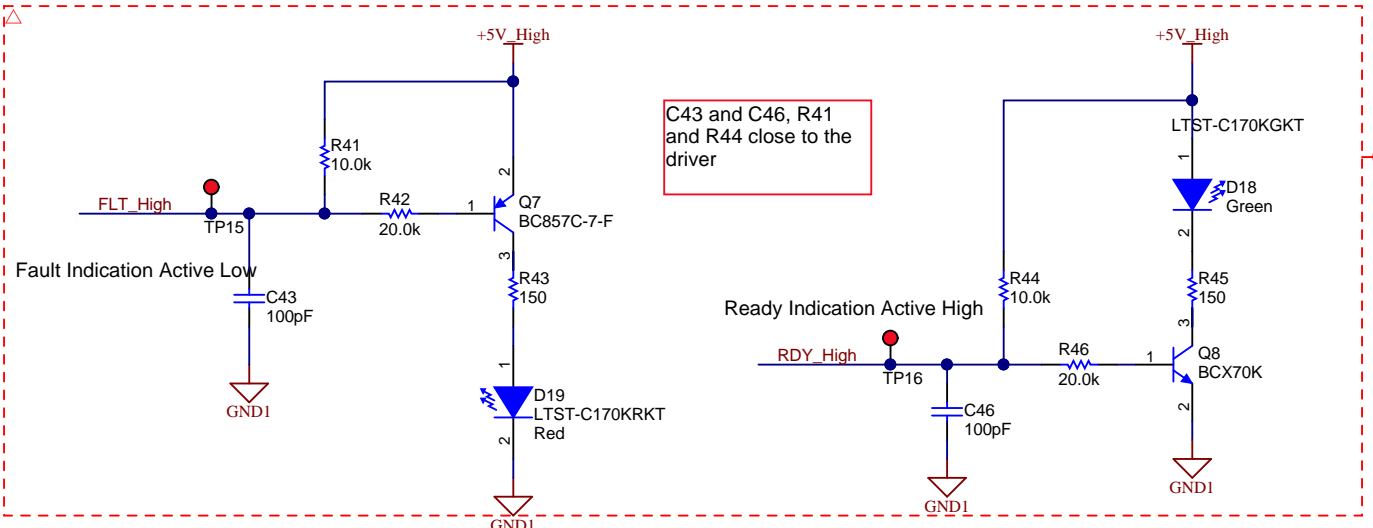
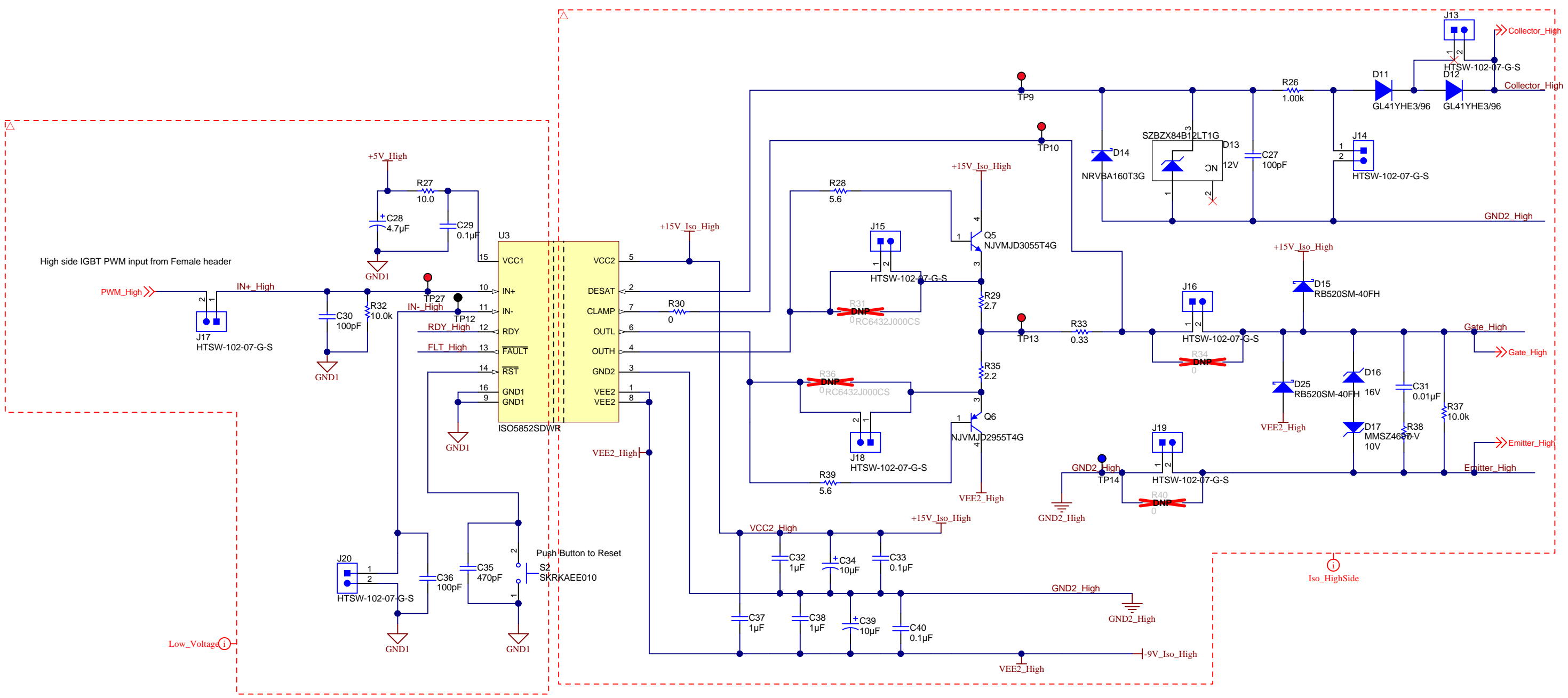


**Isolated IGBT Gate Driver**



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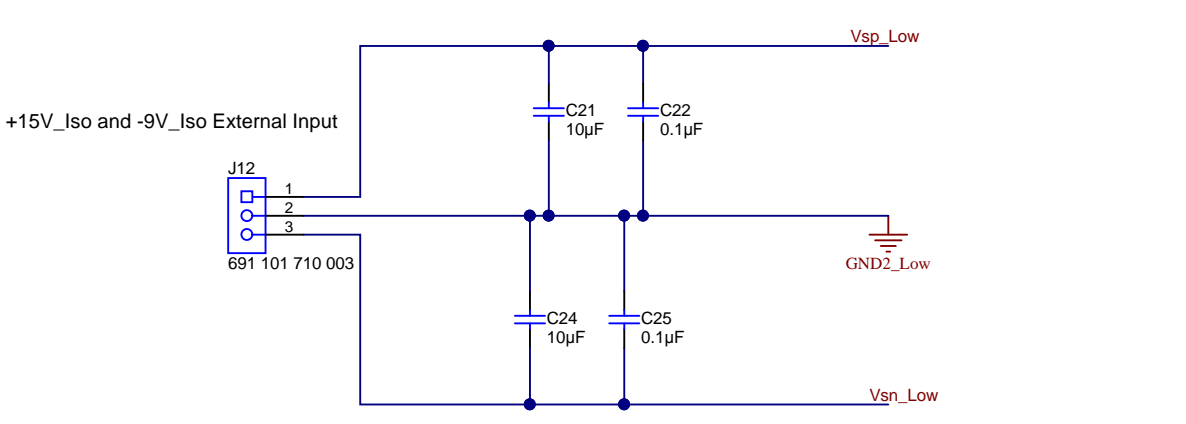
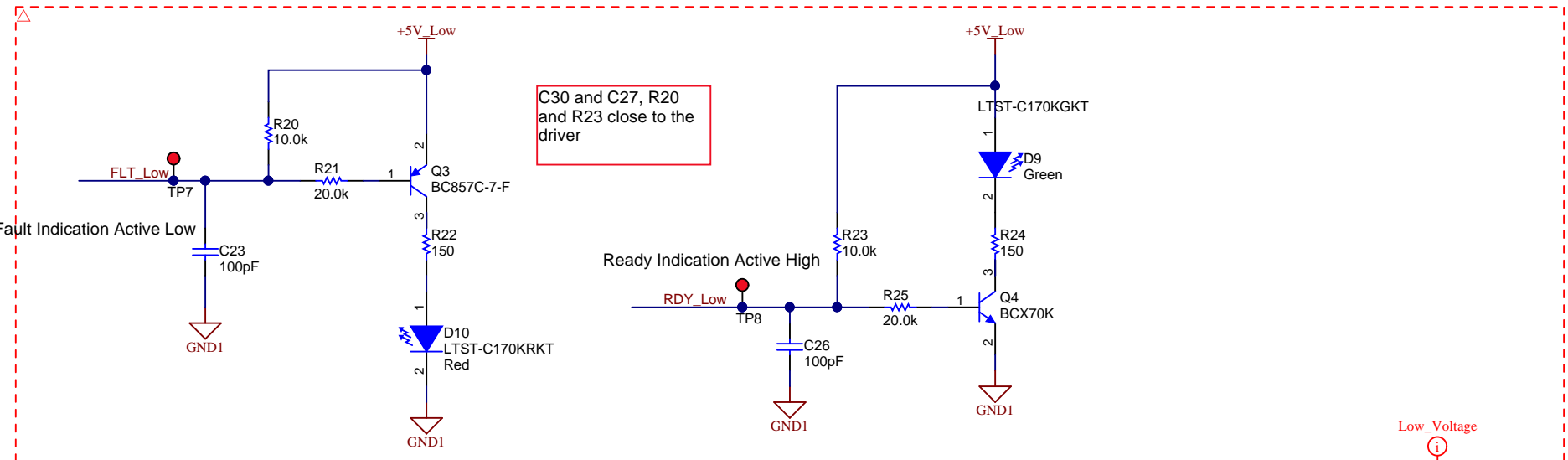
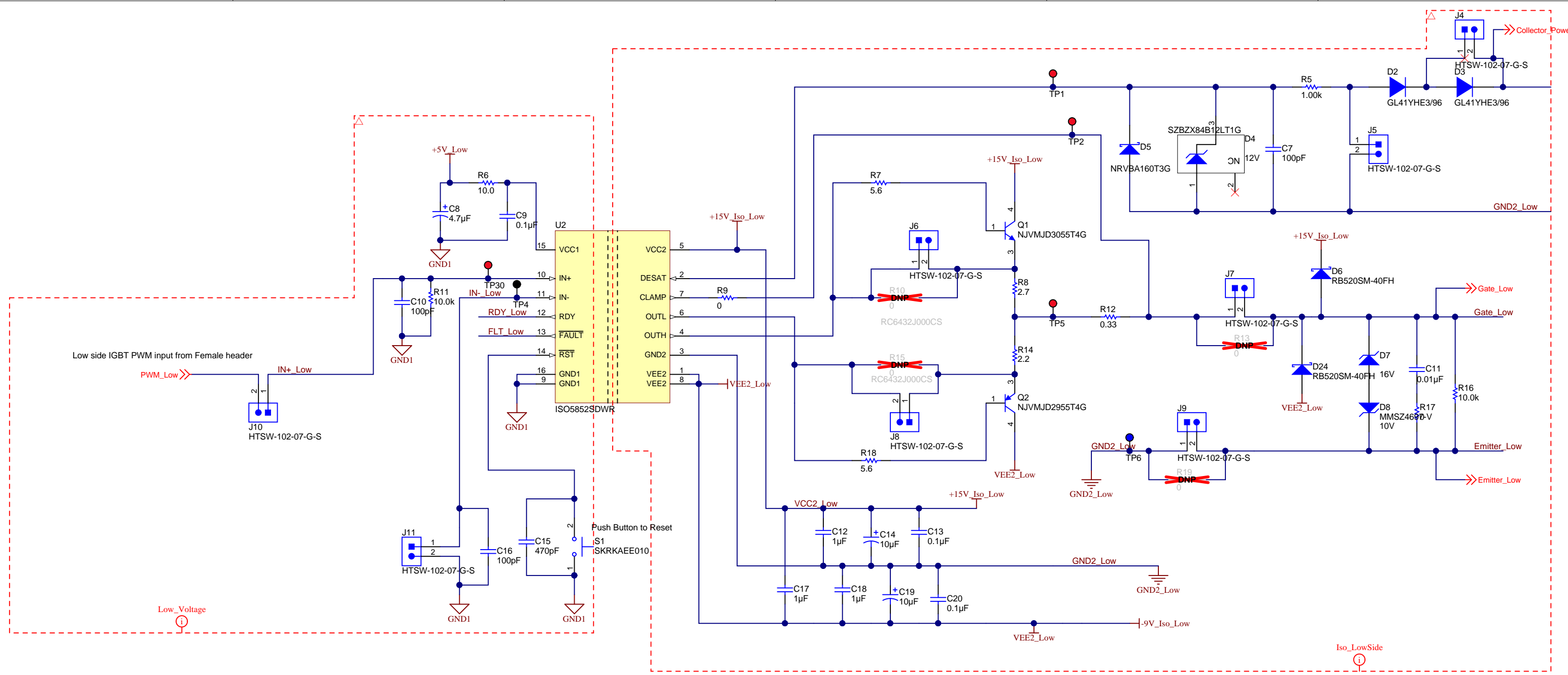
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Number: TIDA-00794	Rev: E1	Sheet Title: Block Diagram	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 7	
Drawn By: X. Gong	File: GateDriverCoverSheet.SchDoc	Size: B	
Engineer: X. Gong	Contact: http://www.ti.com/support		



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Number: TIDA-00794	Rev: E1	Sheet Title: Gate Driver Top
SVN Rev: Version control disabled		Sheet: 2 of 7
Drawn By: X.Gong	File: Gate Driver Top.SchDoc	Size: B
Engineer: X. Gong	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

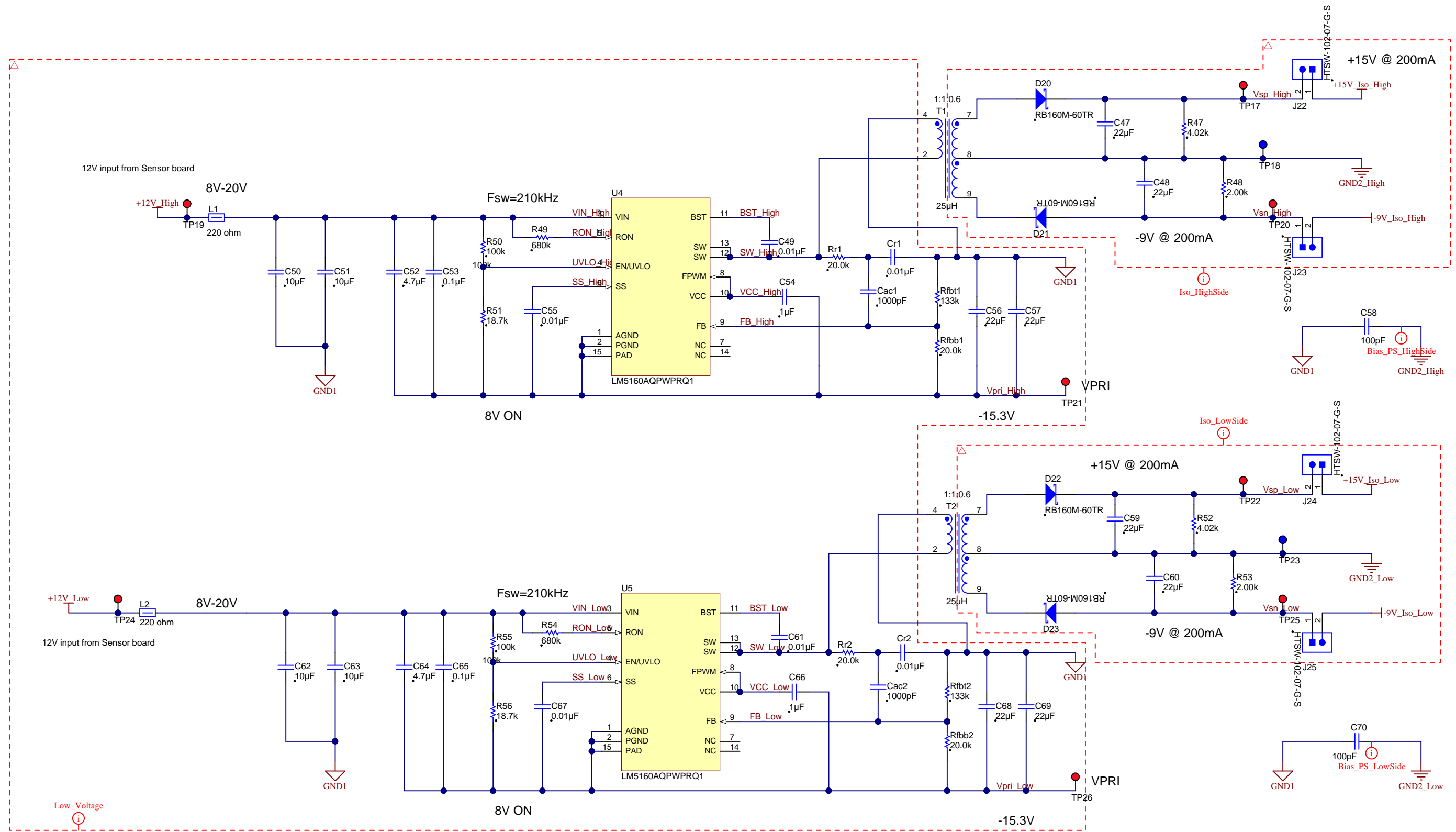




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Number: TIDA-00794	Rev: E1	Sheet Title: Gate Driver Bottom
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 7
Drawn By: X. Gong	File: Gate Driver Bottom.SchDoc	Size: B
Engineer: X. Gong	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



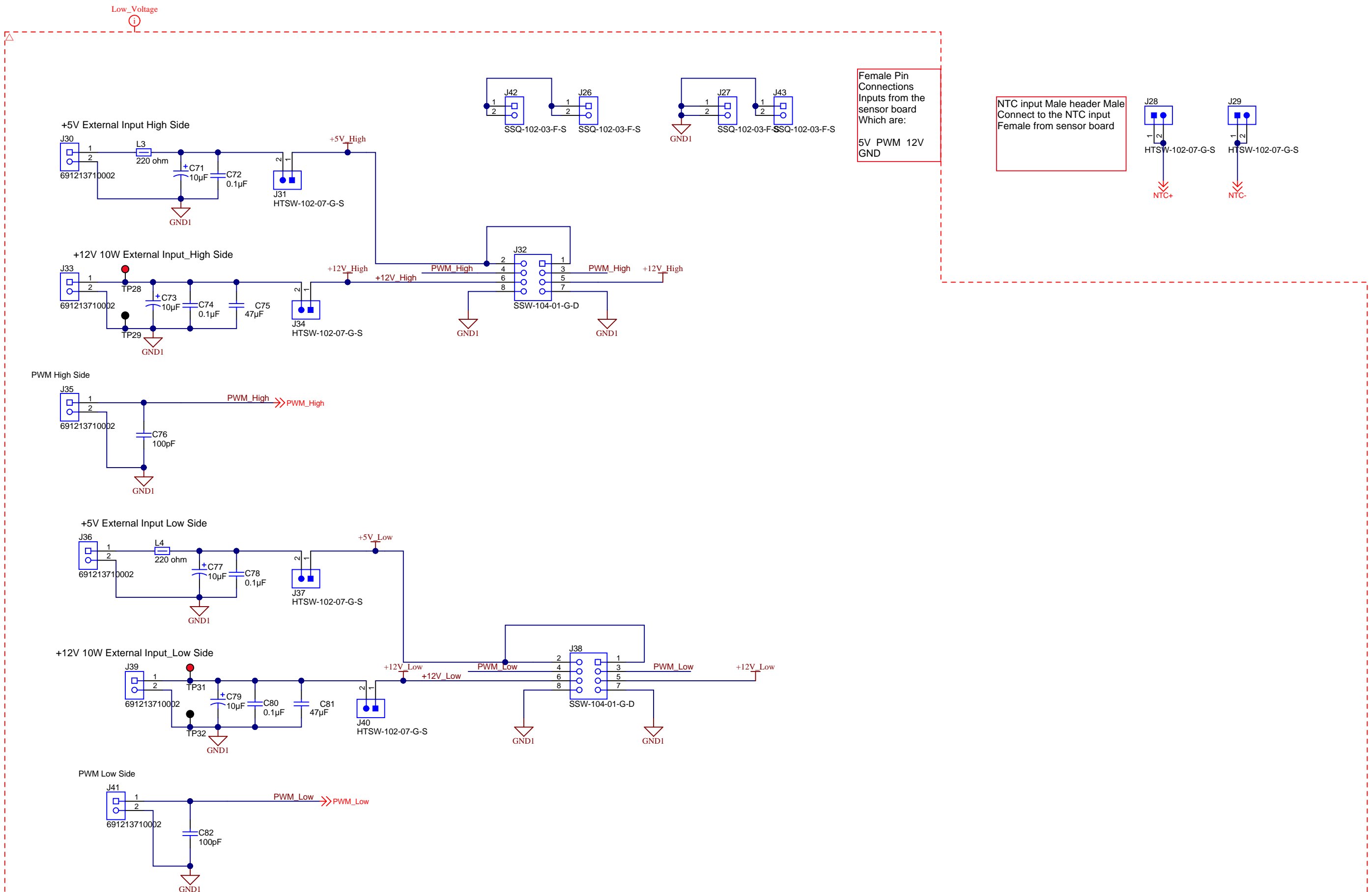


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Number: TIDA-00794	Rev: E1	Sheet Title: Power Supply
SVN Rev: Version control disabled		Assembly Variant: 001
Drawn By: X. Gong		File: Power Supply_SchDoc
Engineer: X. Gong		Size: B
	Sheet: 4 of 7	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>



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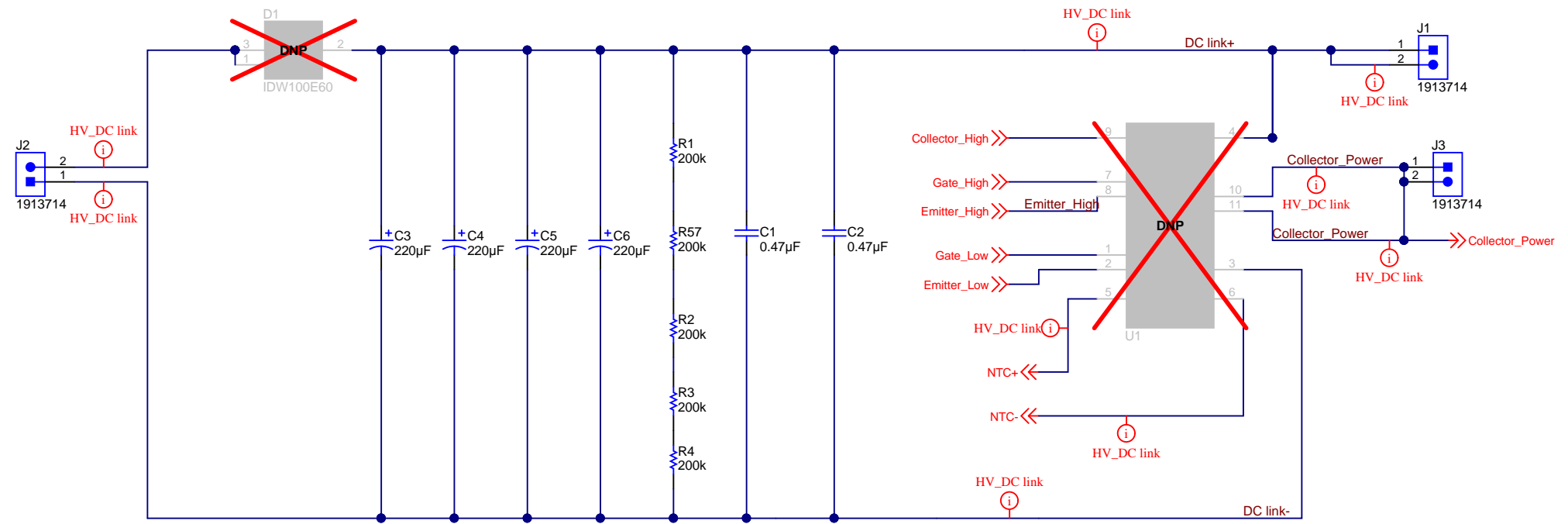


Female Pin Connections  
Inputs from the sensor board  
Which are:  
5V PWM 12V  
GND

NTC input Male header Male  
Connect to the NTC input  
Female from sensor board

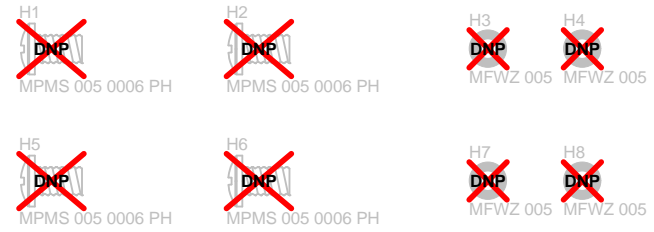
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TID #: TIDA-00794	Project Title: Thermal Protection of IGBT Modules for HEV/EV Tr			
Number: TIDA-00794	Rev: E1	Sheet Title: Connectors		
SVN Rev: Version control disabled		Sheet: 5 of 7		
Drawn By: X. Gong		File: Connectors.SchDoc		
Engineer: X. Gong		Size: B		
		Contact: http://www.ti.com/support		



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Number: TIDA-00794	Rev: E1	Assembly Variant: 001	
SVN Rev: Version control disabled	File: DC links.SchDoc	Sheet: 6 of 7	
Drawn By: X. Gong	Engineer: X. Gong	Contact: http://www.ti.com/support	



H9  
MECH  
1913578

H10  
MECH  
1913578

H11  
MECH  
1913578



PCB Number: TIDA-00794  
PCB Rev: E1

PCB  
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PCB  
LOGO  
Pb-Free Symbol

<sup>A</sup> You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
Assembly Note  
This Assembly Note will show in the PcbDoc and associated outputs

ZZ2  
Assembly Note  
This Assembly Note will show in the PcbDoc and associated outputs

ZZ3  
Assembly Note  
This Assembly Note will show in the PcbDoc and associated outputs

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